Electronic Acknowledgement Receipt			
EFS ID:	1400066		
Application Number:	10810965		
International Application Number:			
Confirmation Number:	9818		
Title of Invention:	Novel method to improve bump reliability for flip chip device		
First Named Inventor/Applicant Name:	Yen-Ming Chen		
Customer Number:	47390		
Filer:	Daniel R. McClure		
Filer Authorized By:			
Attorney Docket Number:	TS01-0413C		
Receipt Date:	26-DEC-2006		
Filing Date:	26-MAR-2004		
Time Stamp:	17:45:45		
Application Type:	Utility		

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Appeal Brief Filed	00463949.pdf	179277	no	19
Warnings:					

Information:					
Total Files Size (in bytes):	179277				

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.